

Title (en)
ELECTRONICS COOLING SYSTEM

Title (de)
ELEKTRONISCHES KÜHLSYSTEM

Title (fr)
SYSTÈME DE REFROIDISSEMENT DE DISPOSITIFS ÉLECTRONIQUES

Publication
EP 3656190 A1 20200527 (EN)

Application
EP 18750068 A 20180719

Priority
• US 201762534627 P 20170719
• US 2018042945 W 20180719

Abstract (en)
[origin: WO2019018681A1] An electronics cooling system (42) with an electronics enclosure (40) that is hermetically sealed. The system (42) includes a heat exchanger (116) that exchanges heat between a first cooling fluid (108) within the electronics enclosure (40) and a second cooling fluid (118) of a vapor compression system (14). A fan (124) circulates the first cooling fluid (108) within the electronics enclosure (40). The electronics cooling system (42) may also include a baffle system (126) within the electronics enclosure (40) that directs the first cooling fluid (108) over one or more electronic components (114) disposed within the electronics enclosure (40) to cool the one or more electronic components (114).

IPC 8 full level
H05K 5/02 (2006.01); **H05K 7/20** (2006.01)

CPC (source: CN EP KR)
H05K 5/0212 (2022.08 - EP KR); **H05K 7/20145** (2013.01 - CN); **H05K 7/20172** (2013.01 - CN); **H05K 7/202** (2013.01 - EP KR); **H05K 7/20309** (2013.01 - CN); **H05K 7/20318** (2013.01 - CN); **H05K 7/20327** (2013.01 - CN); **H05K 7/20354** (2013.01 - CN); **H05K 7/20909** (2013.01 - EP KR)

Citation (examination)
• US 2016174411 A1 20160616 - LEE YUNG KOO [KR], et al
• WO 2012081056 A1 20120621 - PANASONIC CORP [JP], et al
• See also references of WO 2019018681A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

DOCDB simple family (publication)
WO 2019018681 A1 20190124; CN 111096091 A 20200501; CN 116261308 A 20230613; EP 3656190 A1 20200527; JP 2020528217 A 20200917; JP 2022177184 A 20221130; JP 7412064 B2 20240112; KR 102435795 B1 20220825; KR 20200024932 A 20200309; TW 201909720 A 20190301; TW I826384 B 20231221

DOCDB simple family (application)
US 2018042945 W 20180719; CN 201880059353 A 20180719; CN 202310356853 A 20180719; EP 18750068 A 20180719; JP 2020502268 A 20180719; JP 2022148768 A 20220920; KR 20207004108 A 20180719; TW 107124967 A 20180719